



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT: Shiuh-Hui Steven Chen EXAMINER: Nguyen, Donghai D.  
SERIAL NO.: 10/058,650 GROUP: 3729  
FILED: 01/28/2002 CASE NO.: AP01985  
TITLED: Method of Separating And Handling A Thin Semiconductor Die On A Wafer

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Certificate of Transmission under 37 CFR 1.8	
I hereby certify that this correspondence is being mailed to the United States Patent and Trademark Office.	
on <u>March 25, 2004</u>	
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Name of applicant, assignee, or Registered Representative	Date
<u><i>Nanette Chen</i></u>	
Signature	

AMENDMENT

Mail Stop Non-Fee Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

In response to the Office Action dated March 17, 2004 in the above captioned matter,  
please enter the following amendment and response: